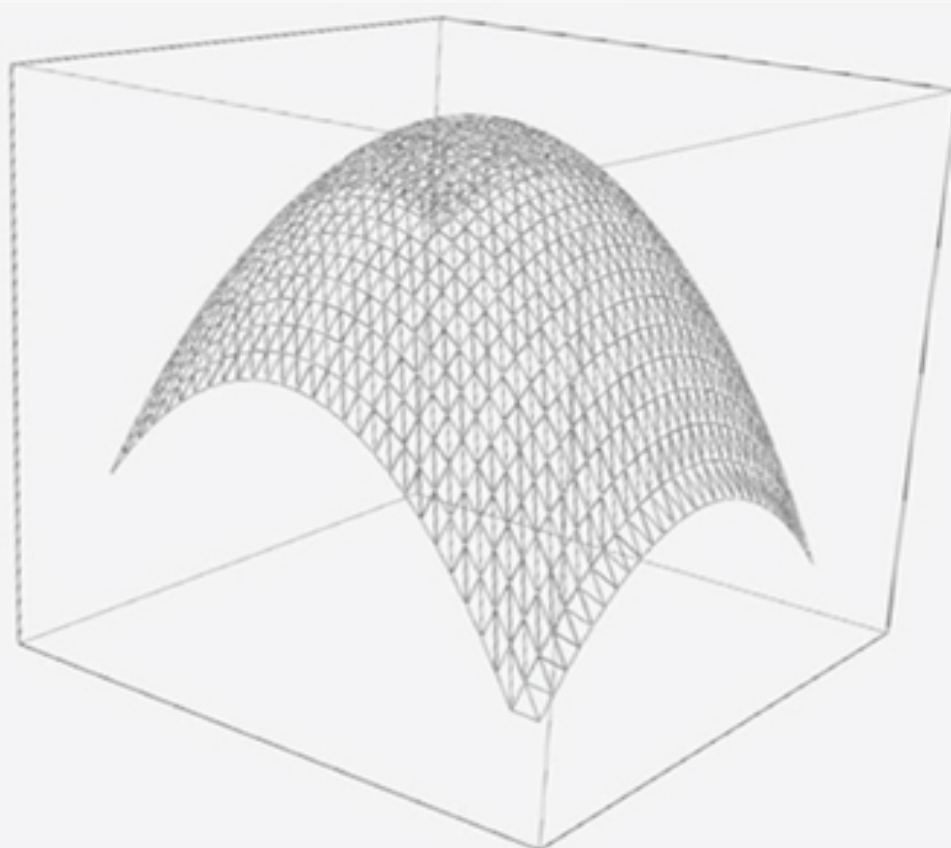


Wiley Series in Probability and Statistics

RESPONSE SURFACE METHODOLOGY

PROCESS AND PRODUCT OPTIMIZATION
USING DESIGNED EXPERIMENTS

FOURTH EDITION



RAYMOND H. MYERS
DOUGLAS C. MONTGOMERY
CHRISTINE M. ANDERSON-COOK

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RESPONSE SURFACE METHODOLOGY

Process and Product Optimization Using Designed Experiments

Fourth Edition

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Figure 6.1 Second-order system displaying a maximum. (a) Contour plot. (b) Response surface.

Figure 6.2 Second-order system displaying a minimum. (a) Contour plot. (b) Response surface.

Figure 6.3 Second-order system displaying a saddle point. (a) Contour plot. (b) Response surface.

Figure 6.4 Canonical form of the second-order model.